



Full Material Declaration for attached parts list

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Declarations authorised by:
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Declaration effective from: 06 December 2016 [Approved on 17 November 2025, 11:30 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.21%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.13%
			Silicon	7440-21-3	99.87%
Die attach	Lead and Lead alloys	1.27%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	19.77%	Carbon black	1333-86-4	0.25%
			Phenol, polymer with formaldehyde	9003-35-4	9.75%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz (SiO2)	14808-60-7	15%
			Silicon dioxide	60676-86-0	65%
Leadfinish	Tin plating	2.1%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	75.65%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
DO-15 (ZM) HF	Diode axial	0.361	g